

ISOFRAX™ BOARD

Isofrax® 1260 Board is based on a revolutionary new fiber with a unique, patented silica-magnesia chemistry. Designed to be used in a wide variety of demanding, high temperature applications, Isofrax has very high solubility in simulated body fluids and meets the European and German regulatory requirements.

Isofrax Boards are the result of long-term research and development by Unifrax to produce a high temperature, low thermal conductivity board that has the characteristics required in many applications at temperatures up to 1260°C.

General Characteristic

Isofrax Boards have these outstanding characteristics:

- High temperature stability (up to 1260°C).
- Low thermal conductivity.
- Good flexural and compressive strength.
- Easy to saw, drill and die-cut.
- Excellent thickness control.
- Low warpage.
- Exceptional surface finish.

Chemical Analysis

SiO ₂	72 - 77
MgO	19 - 26
Al ₂ O ₃	<1.0
Trace Elements	<4.0

Typical Physical Properties

Colour	Blueish-white
Classification Temperature	1260°C
Melting Point	>1500°C
Fiber Diameter	3.0 to 5.0
Modulus of Rupture (as received)	> 6.5 x 10 ⁹ Pa
Density	200 – 300 kg/m ³



Thermal Conductivity Data (W/mK)

400°C	0.07
600°C	0.10
800°C	0.14
1000°C	0.19

Typical Applications

- Rigid high temperature gaskets and seals.
- Domestic boiler heat exchanger linings.
- Trough/distribution linings for conveying aluminium.
- Fire protection systems.
- Heat shields for personnel protection.
- Flare stack linings.
- Hot gas duct linings.
- Refractory backup for brick and castable.

Availability

Standard Thickness (mm)	Quantity per carton
5	16
10	10
15	8
25	4
35	3
50	2

- Standard size: 1000 x 500mm
- Other thicknesses available on request, subject to order.

Data are average results conducted under standard procedures and are subject to variation. Results should not be used for specification purposes.